Schottky barrier diodes in small packages Rev. 06 — 21 December 2006

**Product data sheet** 

### 1. Product profile

### 1.1 General description

Planar Schottky barrier diodes with an integrated guard ring for stress protection. Encapsulated in small Surface-Mounted Device (SMD) plastic packages.

#### Table 1.Product overview

Type number	Package		Configuration
	NXP	JEITA	
1PS76SB21	SOD323	SC-76	single
BAT721	SOT23	-	single
BAT721A	SOT23	-	dual common anode
BAT721C	SOT23	-	dual common cathode
BAT721S	SOT23	-	dual series

### 1.2 Features

- Low forward voltage
- Small SMD plastic packages
- Low capacitance

#### **1.3 Applications**

- Ultra high-speed switching
- Voltage clamping
- Line termination
- Reverse polarity protection

### 1.4 Quick reference data

Table 2.	Quick reference data					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Per diode	)					
I <sub>F</sub>	forward current		-	-	200	mA
V <sub>R</sub>	reverse voltage		-	-	40	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 200 mA	<u>[1]</u> -	-	550	mV



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## 2. Pinning information

Pin	Description	Simplified outline	Symbol
1PS76SB2	1		
1	cathode	[1]	_ /
2	anode		1 <u>F</u> 2 sym001
BAT721			
1	anode		
2	not connected	3	3
3	cathode	1 2 006aaa144	1 2 n.c. 006aaa436
BAT721A			
1	cathode (diode 1)		
2	cathode (diode 2)	3	3
3	anode (diode 1), anode (diode 2)	1 2 006aaa144	1 2 006aaa439
BAT721C			
1	anode (diode 1)		
2	anode (diode 2)	3	3
3	cathode (diode 1), cathode (diode 2)	1 2 006aaa144	1 2 006aaa438
BAT721S			
1	anode (diode 1)		
2	cathode (diode 2)	3	3
3	cathode (diode 1), anode (diode 2)	1 2 006aaa144	1 2 006aaa437

[1] The marking bar indicates the cathode.

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### 3. Ordering information

Table 4. Orde	ering inform	ation				
Type number	Package	ackage				
	Name	Description	Version			
1PS76SB21	SC-76	plastic surface-mounted package; 2 leads	SOD323			
BAT721	-	plastic surface-mounted package; 3 leads	SOT23			
BAT721A						
BAT721C						
BAT721S						

### 4. Marking

Table 5.   Marking codes	
Type number	Marking code <sup>[1]</sup>
1PS76SB21	S1
BAT721	L7*
BAT721A	L8*
BAT721C	L9*
BAT721S	L0*

[1] \* = -: made in Hong Kong

\* = p: made in Hong Kong

- \* = t: made in Malaysia
- \* = W: made in China

### 5. Limiting values

#### Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
V <sub>R</sub>	reverse voltage		-	40	V
I <sub>F</sub>	forward current		-	200	mA
I <sub>FSM</sub>	non-repetitive peak forward current	half sine wave; JEDEC method; t <sub>p</sub> = 8.3 ms	-	1	A
Tj	junction temperature		-	125	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

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#### **Thermal characteristics** 6.

Table 7.	Thermal characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Per diode	)					
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	<u>[1]</u>			
	1PS76SB21		-	-	450	K/W
	BAT721		-	-	500	K/W
	BAT721A		-	-	500	K/W
	BAT721C		-	-	500	K/W
	BAT721S		-	-	500	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

#### **Characteristics** 7.

Table 8. $T_{amb} = 25$	°C unless otherwise	specified.				
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Per diode	)					
V <sub>F</sub>	V <sub>F</sub> forward voltage	I <sub>F</sub> = 10 mA	<u>[1]</u> _	-	300	mV
		I <sub>F</sub> = 100 mA	<u>[1]</u> _	-	420	mV
		I <sub>F</sub> = 200 mA	<u>[1]</u> _	-	550	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 30 V	-	-	15	μΑ
		$V_R$ = 30 V; $T_j$ = 100 °C	-	-	3	mA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 0 V; f = 1 MHz	-	40	50	pF

T-1-1- 0 

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## 8. Package outline



### 9. Packing information

#### Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description	Packing	Packing quantity		
			3000	10000		
1PS76SB21	SOD323	4 mm pitch, 8 mm tape and reel	-115	-135		
BAT721	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235		
BAT721A						
BAT721C						
BAT721S						

[1] For further information and the availability of packing methods, see Section 13.

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### **10. Soldering**



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## **11. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes			
1PS76SB21_BAT721_SER_6	20061221	Product data sheet	-	1PS76SB21_BAT721 _SER_5			
Modifications:	<ul> <li>Amended T</li> </ul>	able 10 "Revision history"					
1PS76SB21_BAT721_SER_5	20061205	Product data sheet	-	BAT721_SERIES_4 1PS76SB21_3			
Modifications:		of this data sheet has been of NXP Semiconductors.	n redesigned to comply	y with the new identity			
	<ul> <li>Legal texts</li> </ul>	have been adapted to the	new company name w	here appropriate.			
	<ul> <li>This data sl 1PS76SB2<sup>-</sup></li> </ul>	heet is a combination of da 1_3.	ata sheets BAT721_SE	RIES_4 and			
	Table 1 "Property of the second se	oduct overview": added					
	Section 1.2	"Features": amended					
	Section 1.3	"Applications": amended					
	<ul> <li>Table 2 "Qu</li> </ul>	iick reference data": added					
	<ul> <li><u>Table 5 "Marking codes"</u>: for 1PS76SB21 amended</li> </ul>						
	• Table 5 "Ma	arking codes": enhanced ta	ble note section				
	Table 6 "Lin	<ul> <li><u>Table 6 "Limiting values"</u>: indication per diode added</li> </ul>					
	• Table 6 "Lin	<ul> <li><u>Table 6 "Limiting values"</u>: for 1PS76SB21 I<sub>FSM</sub> condition amended</li> </ul>					
	<ul> <li><u>Table 6 "Limiting values"</u>: T<sub>amb</sub> ambient temperature added</li> </ul>						
	<ul> <li><u>Table 7 "Thermal characteristics"</u>: indication per diode added</li> </ul>						
	• Table 7: R <sub>th</sub>	<sub>(j-a)</sub> thermal resistance fror	n junction to ambient c	ondition amended			
	Table 8 "Ch	<ul> <li><u>Table 8 "Characteristics</u>": indication per diode added</li> </ul>					
	<ul> <li><u>Table 8 "Characteristics</u>": reference to <u>Table note 1</u> amended</li> </ul>						
	<ul> <li><u>Table 8</u>: for 1PS76SB21 C<sub>d</sub> minimum value changed to typical value</li> </ul>						
	• Figure 1 and 2: amended						
	<ul> <li>Figure 4 and 5: superseded by minimized package outlines</li> </ul>						
		Packing information": adde	d				
		"Soldering": added					
	Section 12	"Legal information": update	ed				
BAT721_SERIES_4	20040315	Product specification	-	BAT721_SERIES_3			
1PS76SB21_3	20040126	Product specification	-	1PS76SB21_2			

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### 12. Legal information

#### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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